

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) An electronic component comprising an electrically conductive relief structure (3) on a surface of an electrically insulating substrate (2), which structure comprises a salt of a poly (3,4 ~~oxygen~~-substituted thiophene) as electrically conductive material, wherein the relief structure (3) contains a polyacid salt of a poly-3, 4-alkylenedioxythiophene, in which the alkylene group is chosen from the group consisting of a methylene group, an 1,2-ethylene group, a 1,3-propylene group and a 1,2-cyclohexylene group, which groups are optionally substituted, and the relief structure (3) comprises ~~at least one electrode~~ a plurality of electrodes(32), which are spaced at a distance of 10 μ m or less from one another.

2. (Original) An electronic component as claimed in Claim 1, the optionally present substitution contains a sulphonic acid.

3. (Cancelled)

4. (Previously Amended) An electronic component as claimed in Claim 3, characterized in that neighboring tracks form a pair of a source and a drain electrode, at least one of which is fork-shaped, the source and the drain electrode being

interdigitated.

5. (Original) An electronic component as claimed in Claim 1, characterized in that the component comprises a second electrically conductive relief structure (6) separated from said relief structure (3) at least by an insulating layer (5).

6. (Original) An electronic component as claimed in Claim 5, characterized in that the second relief structure (6) contains a salt of a poly-3,4-alkylenedioxythiophene, in which the alkylene group is chosen from a set consisting of an optionally C₁ to C₁₂-alkyl- or phenylsubstituted methylene group, an optionally C₁ to C₁₂-alkyl- or phenylsubstituted 1,2-ethylene group, a 1,3-propylene group, and a 1,2-cyclohexylene group.

7. (Previously Amended) An electronic component as claimed in Claim 5, characterized in that the component comprises a field effect transistor (1).

8. (Original) An electronic component as claimed in Claim 1, characterized in that the component substantially consists of organic polymeric material.

9. (Currently Amended) A method of manufacturing a relief structure (3) on a substrate (2), comprising the steps of
- forming a radiation-sensitive composition which contains a photochemical initiator and a salt of an anion of a polyacid and a poly-3,4-alkylenedioxythiophene, in which the alkylene group is chosen from a set consisting of an optionally

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C₁ to C₁₂- alkyl- or phenyl-substituted methylene group, an optionally C₁ to C₁₂-alkyl- or phenyl-substituted 1,2-ethylene group, a 1,3-propylene group and, a 1,2-cyclohexylene group;
- providing said radiation-sensitive composition on the substrate so as to form a layer;
- irradiating said layer in accordance with to a desired pattern, thereby obtaining irradiated areas and non-irradiated areas; and
- developing said layer so as to form the electrically conductive relief structure in the desired pattern, wherein the relief structure comprises neighboring tracks, which lie at a distance of 10 μ m or less from one another.

10. (Original) A method as claimed in Claim 9, characterized in that the non-irradiated areas are removed in the developing step.

11. (Previously Amended) A method as claimed in Claim 9, characterized in that the method comprises, after the developing step, the additional step of doping said relief structure with an organic compound containing a first functional group selected from polyhydroxy, dihydroxy, carboxyl, lactam and amide, sulphon, sulphoxy, phosphate, and MEA.

